

# CM1457

## L-C EMI Filter Array with ESD Protection, 4-, 6- and 8-Channel

### Description

The CM1457 is an inductor-based (L-C) EMI filter array with ESD protection, which integrates four, six, or eight filters in a CSP form factor with 0.40 mm pitch. Each EMI filter channel of the CM1457 is implemented with the component value of 6 pF – 35 nH – 4.7 pF – 35 nH – 1.8 pF. The cut-off frequency at –3 dB attenuation is 300 MHz and can be used in applications where the data rates are as high as 160 Mbps, while providing greater than –35 dB attenuation over the 800 MHz to 2.7 GHz frequency range. The parts include ESD diodes on every I/O pin and provide a high level of protection against electrostatic discharge (ESD). The ESD protection diodes connected to the external filter ports are designed and characterized to safely dissipate ESD strikes of ±15 kV, which is beyond the maximum requirement of the IEC61000–4–2 international standard.

This device is particularly well suited for wireless handsets, mobile LCD modules and PDAs because of its small package format and easy-to-use pin assignments. In particular, the CM1457 is ideal for EMI filtering and protecting data and control lines for the LCD display and camera interface in mobile handsets.

The CM1457 incorporates *OptiGuard* which results in improved reliability at assembly. It is manufactured with a 0.40 mm pitch and 0.25 mm CSP solder ball to provide up to 28% board space savings vs. competing CSP devices with 0.50 mm pitch and 0.30 mm CSP solder ball.

### Features

- Four, Six or Eight Channels of EMI Filtering
- ±15 kV ESD Protection (IEC 61000–4–2, Contact Discharge) at External Pins
- Greater than –40 dB of Attenuation at 1 GHz MIL–STD–883 International ESD Standard
- Chip Scale Package (CSP) with 0.40 mm Pitch and 0.25 mm CSP Solder Ball which Features Extremely Low Parasitic Inductance for Optimum Filter and ESD Performance
- *OptiGuard* Coating for Improved Reliability at Assembly
- These Devices are Pb–Free and are RoHS Compliant

### Applications

- LCD and Camera Data Lines in Mobile Handsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computers
- Wireless Handsets
- Handheld PCs/PDAs
- LCD and Camera Modules



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WLCSP10  
CP SUFFIX  
CASE 567BJ

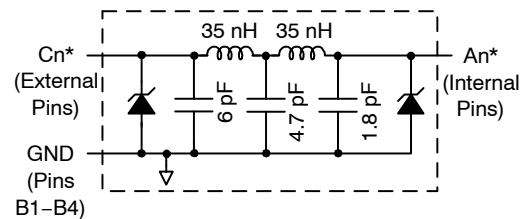


WLCSP15  
CP SUFFIX  
CASE 567BR

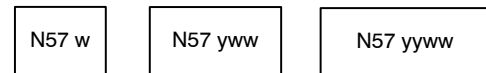


WLCSP20  
CP SUFFIX  
CASE 567BV

### BLOCK DIAGRAM



### MARKING DIAGRAM



CM1457–04 10–Bump CSP	CM1457–06 15–Bump CSP	CM1457–08 20–Bump CSP
N57	=	CM1457–04CP
N57	=	CM1457–06CP
N57	=	CM1457–08CP
w/yyww/yyww	=	date code

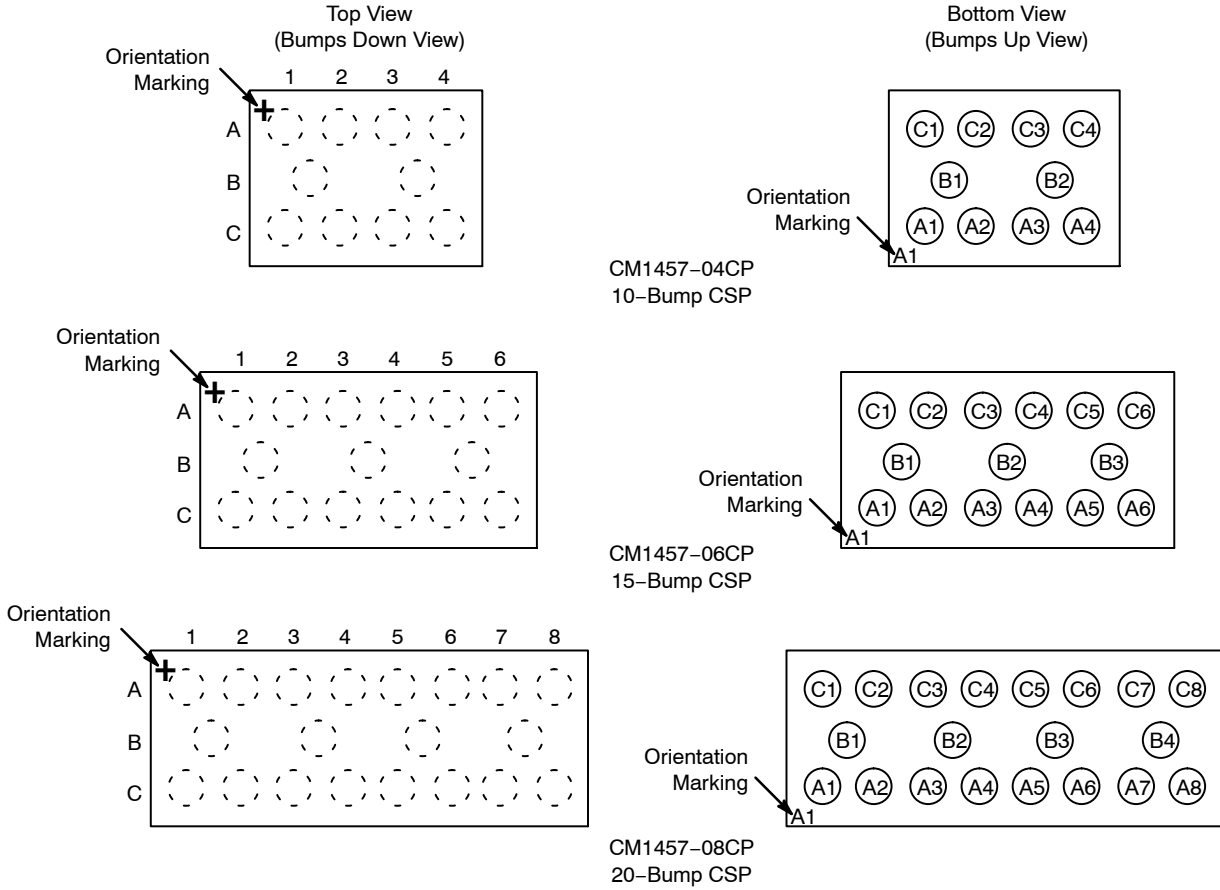
### ORDERING INFORMATION

Device	Package	Shipping†
CM1457–04CP	CSP–10 (Pb–Free)	3500/Tape & Reel
CM1457–06CP	CSP–15 (Pb–Free)	3500/Tape & Reel
CM1457–08CP	CSP–20 (Pb–Free)	3500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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## PACKAGE / PINOUT DIAGRAMS



**Table 1. PIN DESCRIPTIONS**

Pin Number			Pin Description	Pin Number			Pin Description
-04	-06	-08		-04	-06	-08	
A1	A1	A1	Filter #1 (Internal)	C1	C1	C1	Filter #1 (External)
A2	A2	A2	Filter #2 (Internal)	C2	C2	C2	Filter #2 (External)
A3	A3	A3	Filter #3 (Internal)	C3	C3	C3	Filter #3 (External)
A4	A4	A4	Filter #4 (Internal)	C4	C4	C4	Filter #4 (External)
-	A5	A5	Filter #5 (Internal)	-	C5	C5	Filter #5 (External)
-	A6	A6	Filter #6 (Internal)	-	C6	C6	Filter #6 (External)
-	-	A7	Filter #7 (Internal)	-	-	C7	Filter #7 (External)
-	-	A8	Filter #8 (Internal)	-	-	C8	Filter #8 (External)
B1, B2	B1-B3	B1-B4	GND				

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## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC current per Inductor	15	mA
DC Package Power Rating	0.5	W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

**Table 4. ELECTRICAL OPERATING CHARACTERISTICS** (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
L <sub>TOT</sub>	Total Channel Inductance			70		nH
R <sub>TOT</sub>	Total Channel DC Resistance			45		Ω
C <sub>TOT_0V</sub>	Total Channel Capacitance, 0 V bias	0 V dc; 1 MHz, 30 mV rms		20	24	pF
C <sub>TOT_2.5V</sub>	Total Channel Capacitance, 2.5 V bias	2.5 V dc; 1 MHz, 30 mV rms		12.5		pF
V <sub>ST</sub>	Stand-off Voltage	I = 10 μA	5.5			V
I <sub>LEAK</sub>	Diode Leakage Current	V <sub>IN</sub> = +3.3 V		0.1	0.5	μA
V <sub>SIG</sub>	Signal Clamp Voltage Positive Clamp Negative Clamp	I <sub>LOAD</sub> = 10 mA I <sub>LOAD</sub> = -10 mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V <sub>ESD</sub>	In-system ESD Withstand Voltage a) Contact Discharge per IEC 61000-4-2 standard, Level 4 ( <b>External Pins</b> ) b) Contact Discharge per IEC 61000-4-2 standard, Level 4 ( <b>Internal Pins</b> )	(Notes 2 and 3)	±15 ±2			kV
f <sub>C</sub>	Cut-off Frequency Z <sub>SOURCE</sub> = 50 Ω, Z <sub>LOAD</sub> = 50 Ω			300		MHz

1. T<sub>A</sub> = 25°C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.
3. Unused pins are left open.

## APPLICATION INFORMATION

Refer to Application Note “The Chip Scale Package”, for a detailed description of Chip Scale Packages offered by ON Semiconductor.

# CM1457

## PERFORMANCE INFORMATION

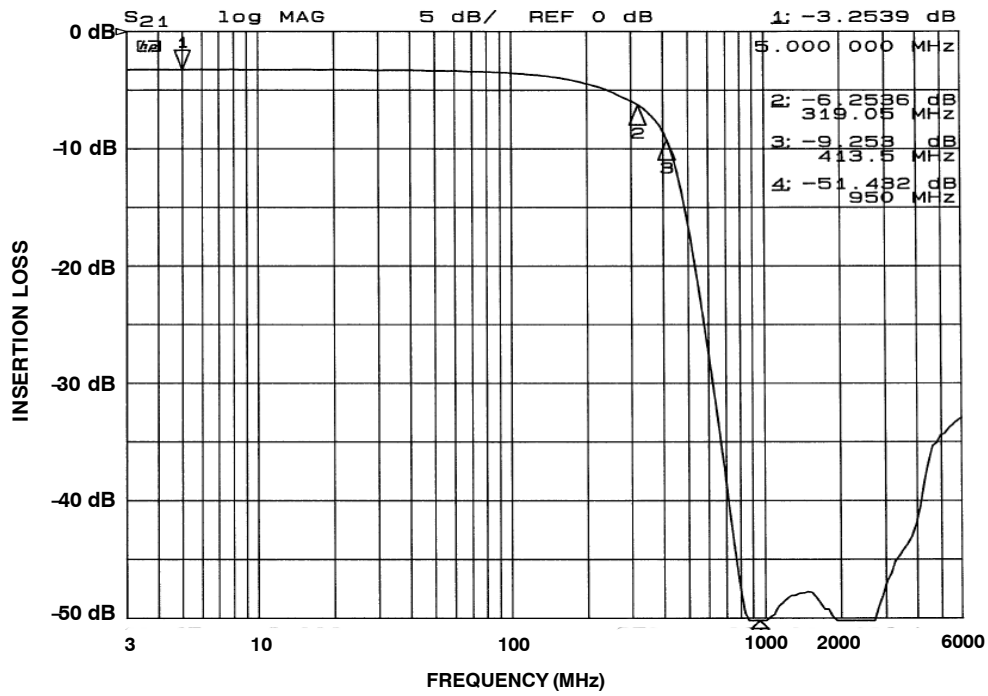


Figure 1. Insertion Loss vs. Frequency (0 V Bias)

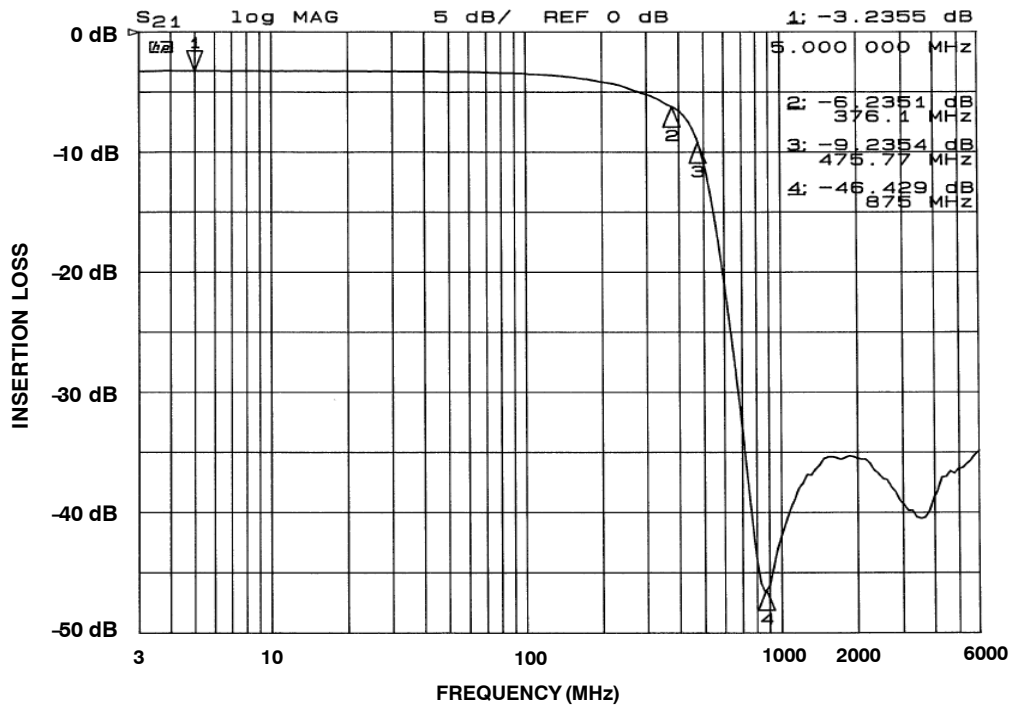


Figure 2. Insertion Loss vs. Frequency (2.5 V Bias)

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

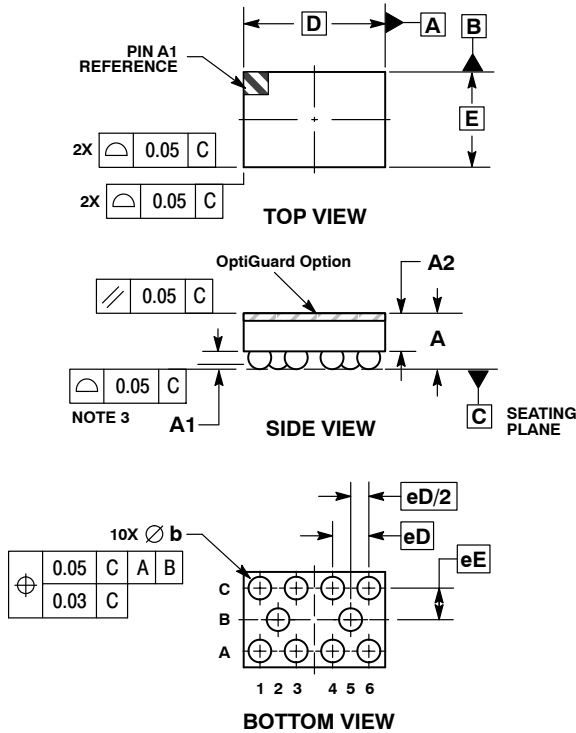
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SCALE 4:1

**WLCSP10, 1.67x1.05**  
CASE 567BJ-01  
ISSUE O

DATE 26 JUL 2010

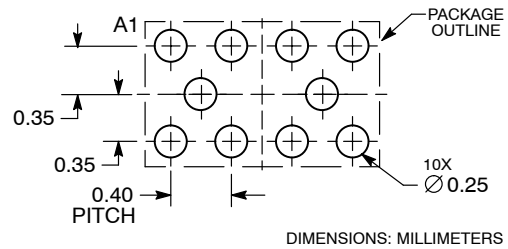


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.54	0.69
A1	0.17	0.24
A2	0.42	REF
b	0.24	0.29
D	1.67	BSC
E	1.05	BSC
eD	0.400	BSC
eE	0.347	BSC

**RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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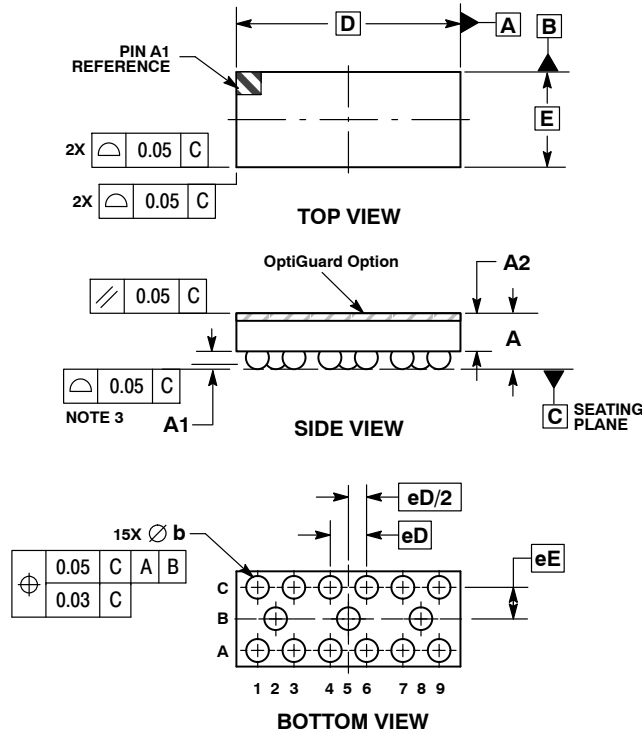
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WLCSP15, 2.47x1.05  
CASE 567BR-01  
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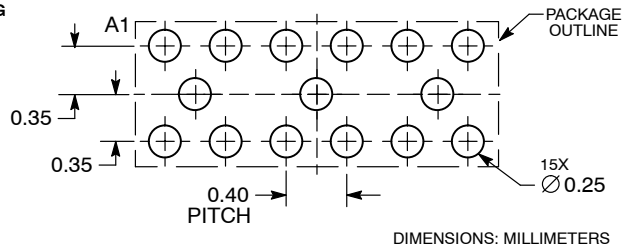


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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

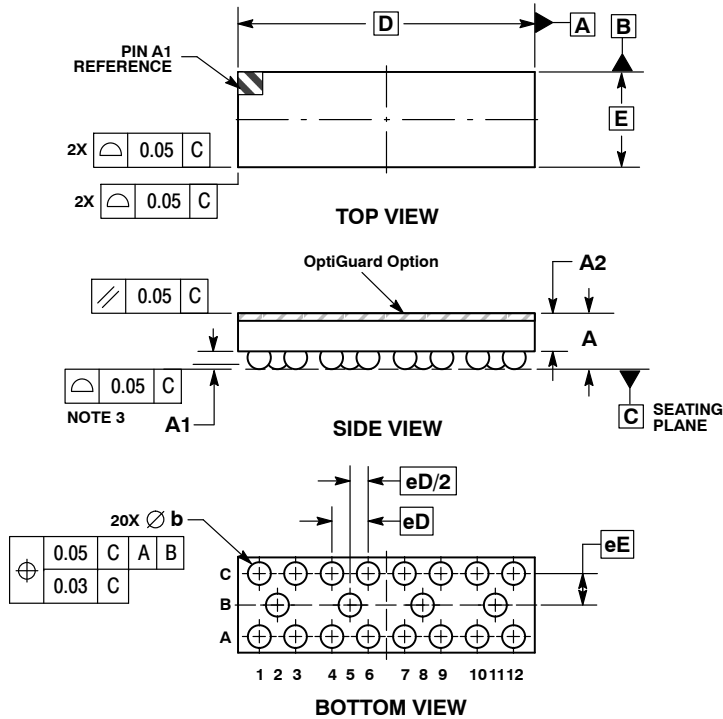
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SCALE 4:1

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CASE 567BV-01  
ISSUE O

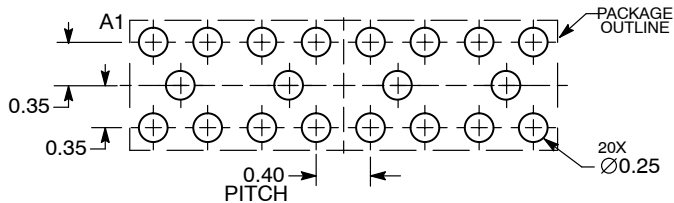
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- NOTES:
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### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

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